



Compact Navigation, Guidance and Control Actuator for Miniature Kinetic Energy Missiles

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Presentation to:

DARPA Smart Structures Technology Interchange Meeting

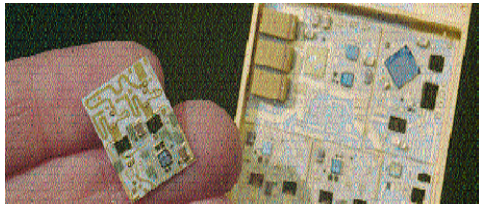
CHAP Kickoff Meeting

Baltimore, MD

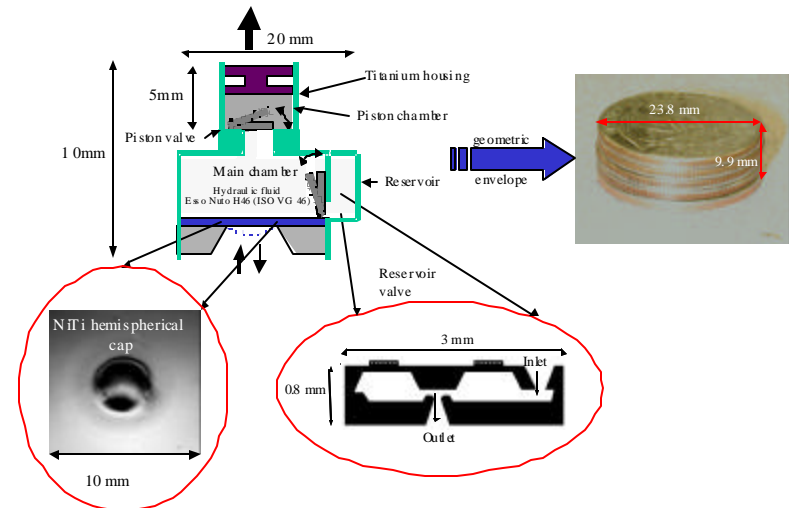
OBJECTIVES AND SCOPE OF THE PROGRAM

DESIGN & FABRICATE NEW COMPACT ACTUATOR COMBINING

- **THIN FILM SHAPE MEMORY ALLOY: HIGH POWER DENSITY & IMPROVED BANDWIDTH**

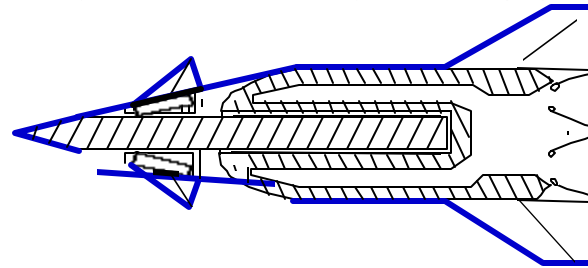


- **HYDRAULIC RECTIFICATION: IMPROVED STROKE**
- **DENSE POWER ELECTRONICS: COMPACT**



TO GUIDE & CONTROL NEXT-GENERATION MISSILES

- **HIGHLY COMPACT**
- **HIGH SPEED**
- **LOW COST**



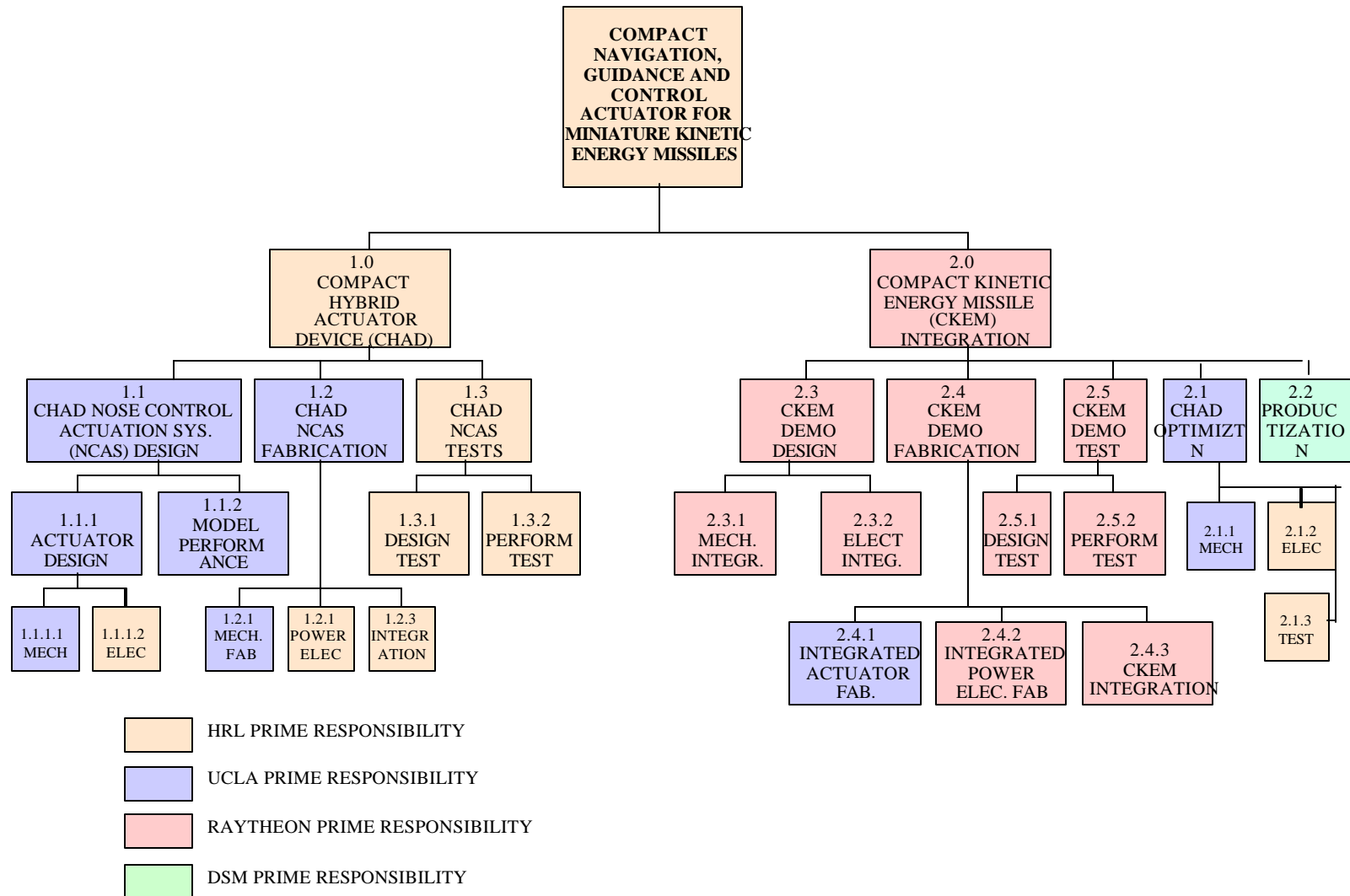
PROJECTED PROGRAM SCHEDULE

TECHNICAL MILESTONE	YEAR ONE				YEAR TWO				YEAR THREE			
	1QTR	2QTR	3QTR	4QTR	1QTR	2QTR	3QTR	4QTR	1QTR	2QTR	3QTR	4QTR
DESIGN FIRST GEN CHAD TO MEET NCAS SPEC												
FABRICATE THIN FILM SMAS 10 mm CAP, 1 mm DEFLECT												
FABRICATE CHAD MECHANICAL ACTUATOR												
POWER ELECTRONICS 16A, 3V												
INTEGRATED CHAD THERMAL & STRUCTURAL TESTS												
NCAS/CHAD REDESIGN FOR CKEM DEMO												
MANUFACTURING/MARKETING ASSESS												
FABRICATE INTEGRATED CKEM DEMO												
REFINED MECHANICAL DESIGN												
FORM FACTOR POWER ELECTRONICS												
CKEM SIMULATED HIL TEST												
DESIGN SIMULATED FLIGHT TEST												
CONTROLLED "FLIGHT" TEST												
	PHASE ONE						PHASE TWO					

**FABRICATION OF FIRST GENERATION
MECHANICAL ACTUATOR & BREADBOARD
POWER ELECTRONICS BY END OF PHASE I.**

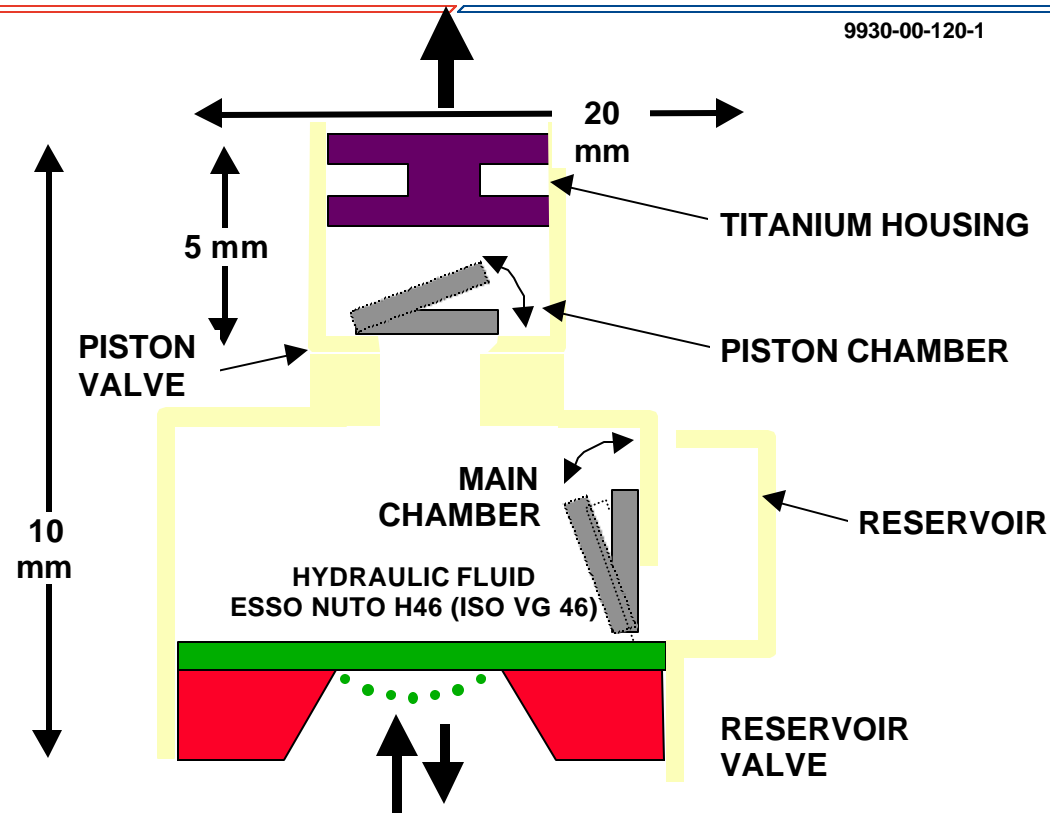
**REFINE DESIGN FOR FORM FACTOR BEGINNING OF
PHASE II.**

HIGHLY LEVERAGED TEAM EFFORT

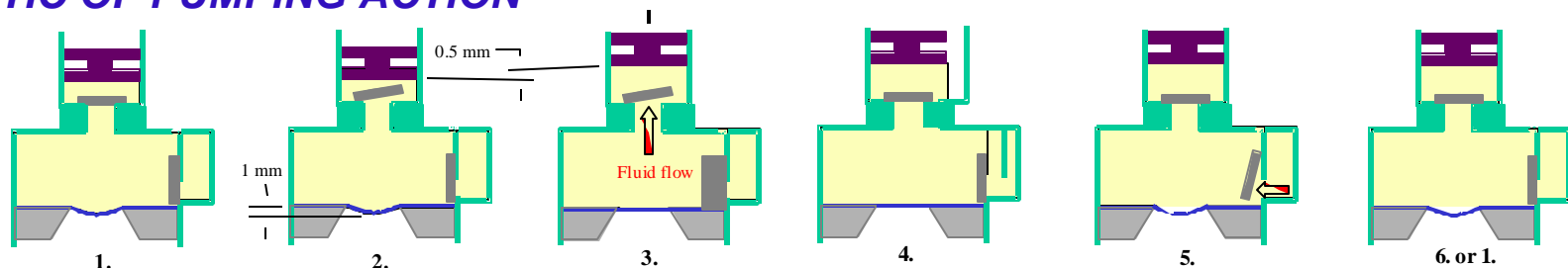


COMPACT HYBRID ACTUATOR DEVICE CONCEPT

9930-00-120-1

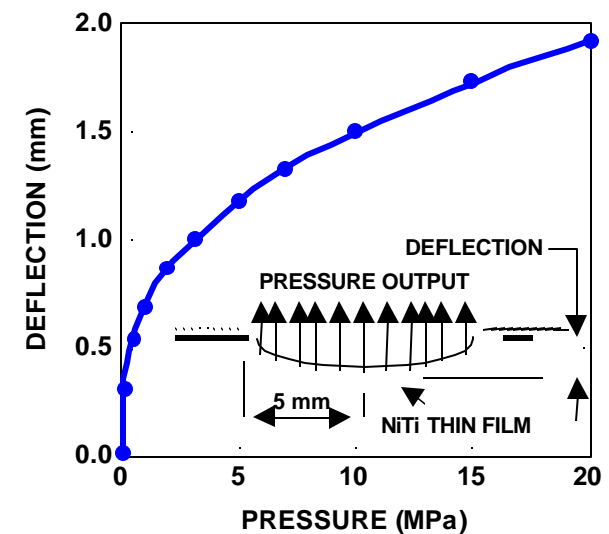
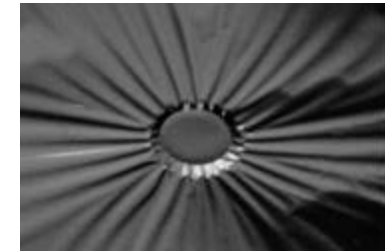


SCHEMATIC OF PUMPING ACTION



KEY TECHNOLOGIES DEMONSTRATED

- *FABRICATION OF THIN FILM NiTi ALLOYS*
- *HIGH MEASURED BANDWIDTH OF THIN FILM SMA*
- *SIMULATED HIGH PRESSURE OUTPUT OF SMA*
- *MICROFABRICATED VALVES USING MEMS TECHNOLOGY*
- *HIGH DENSITY ELECTRONICS*



PROGRAM TECHNOLOGY INSERTION POINTS

